## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Takayuki SAITO et al.

Attn: APPLICATION BRANCH

Serial No. NEW

Attorney Docket No. 2003 1585A

Filed October 30, 2003

THE COMMISSIONER IS AUTHORIZED

TO CHARGE ANY DEFICIENCY IN THE FEES FOR THIS PAPER TO DEPOSIT

SUBSTRATE PROCESSING APPARATUS AND SUBSTRATE PROCESSING METHOD

ACCOUNT NO. 23-0975

COVER LETTER ACCOMPANYING APPLICATION FILED WITHOUT EXECUTED DECLARATION UNDER 37 CFR 1.53(b) AND IN A LANGUAGE

OTHER THAN ENGLISH UNDER 37 CFR 1.52(d)

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Enclosed is a new patent application entitled "SUBSTRATE PROCESSING APPARATUS AND SUBSTRATE PROCESSING METHOD". This application is submitted in the Japanese language under the provisions of 37 CFR 1.52(d).

Furthermore, the present application is submitted under the provisions of 37 CFR 1.53(b), and the application as filed does not include an executed declaration. However, accompanying the application is an unexecuted declaration listing the inventor information.

The application as filed further does not include an executed power of attorney, and accordingly, it is requested that communication initially be directed to the following firm, until an executed power of attorney and declaration are filed:

WENDEROTH, LIND & PONACK, L.L.P. 2033 K Street, N.W., Suite 800 Washington, D.C. 20006-1021

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The required filing fee of \$770.00 is enclosed.

Respectfully submitted,

Takayuki SAITO et al.

Ву

Michael S. Huppert Registration No. 40,268 Attorney for Applicants

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## DECLARATION AND POWER OF ATTORNEY FOR U.S. PATENT APPLICATION

(X) Original () Supplemental () Substitute () PCT () DESIGN

As a below named inventor, I hereby declare that: my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural inventors are named below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

invention entitled:	e named below) of the subject matter wh	nich is claimed and for which a	patent is sought on the
Title: SUBSTRATE PROCESSING	APPARATUS AND SUBSTRATE PRO	CESSING METHOD	
	erial No, file	ed October 30, 2003, and with a	amendments through
, or () the specification in International A	pplication No., filed, and as amended or	(if applicable).	
I hereby state that I have reviewed an any amendment(s) referred to above.	d understand the content of the above-ide	ntified specification, including the	e claims, as amended by
I acknowledge my duty to disclose t defined in Title 37, Code of Federal I	o the Patent and Trademark Office all int Regulations, §1.56.	formation known to me to be man	terial to patentability as
	Title 35, United States Code, §119 (and §1 ted below and have also identified below a ation on which priority is claimed:		
COUNTRY	APPLICATION NO.	DATE OF FILING	PRIORITY CLAIMED
Japan	2002-211524	July 19, 2002	YES
Japan	2002-213078	July 22, 2002	YES
			<u> </u>
subject matter of each of the claims of the first paragraph of Title 35, United defined in Title 37, Code of Federal	e 35, United States Code §120 of any Union of this application is not disclosed in the ped States Code §112, I acknowledge the Regulations, §1.56 which occurred between application:	rior United States application in t duty to disclose information mat	he manner provided by erial to patentability as
subject matter of each of the claims of the first paragraph of Title 35, United defined in Title 37, Code of Federal	of this application is not disclosed in the ped States Code §112, I acknowledge the Regulations, §1.56 which occurred between is application:	rior United States application in t duty to disclose information mat	he manner provided by erial to patentability as ication and the national ED, PENDING,
subject matter of each of the claims of the first paragraph of Title 35, United defined in Title 37, Code of Federal or PCT international filing date of the	of this application is not disclosed in the ped States Code §112, I acknowledge the Regulations, §1.56 which occurred between is application:	rior United States application in t duty to disclose information mat en the filing date of the prior appl STATUS: PATENT	he manner provided by erial to patentability as ication and the national ED, PENDING,
subject matter of each of the claims of the first paragraph of Title 35, United defined in Title 37, Code of Federal or PCT international filing date of the	of this application is not disclosed in the ped States Code §112, I acknowledge the Regulations, §1.56 which occurred between is application:	rior United States application in t duty to disclose information mat en the filing date of the prior appl STATUS: PATENT	he manner provided by erial to patentability as ication and the national ED, PENDING,

And I hereby appoint Michael R. Davis, Reg. No. 25,134; Matthew M. Jacob, Reg. No. 25,154; Warren M. Cheek, Jr., Reg. No. 33,367; Nils Pedersen, Reg. No. 33,145; Charles R. Watts, Reg. No. 33,142; Michael S. Huppert, Reg. No. 40,268; and Jeffrey R. Filipek, Reg. No. 41,471, who together constitute the firm of WENDEROTH, LIND & PONACK, L.L.P., as well as any other attorneys and agents associated with Customer No. 000513, to prosecute this application and to transact all business in the U.S. Patent and Trademark Office connected therewith.

I hereby authorize the U.S. attorneys and agents named herein to accept and follow instructions from <u>WATANABE & HOTTA</u> as to any action to be taken in the U.S. Patent and Trademark Office regarding this application without direct communication between the U.S. attorneys and myself. In the event of a change in the persons from whom instructions may be taken, the U.S. attorneys named herein will be so notified by me.

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I further declare that all statements made herein of my own knowledge are true, and that all statements on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

1st Inventor	Date	
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2nd Inventor	Date	
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5th Inventor	Date	
Masayuki KAMEZAWA		
6th Inventor	Date	
Kenji YAMAGUCHI		
The above application may be more particularly identified	ed as follows:	
U.S. Application Serial No Filing Date October 30, 2003		
Applicant Reference Number <u>GEB2005-US</u> Atty Dock	xet No. <u>2003_1585A</u>	

Title of Invention SUBSTRATE PROCESSING APPARATUS AND SUBSTRATE PROCESSING METHOD